

1.1.1

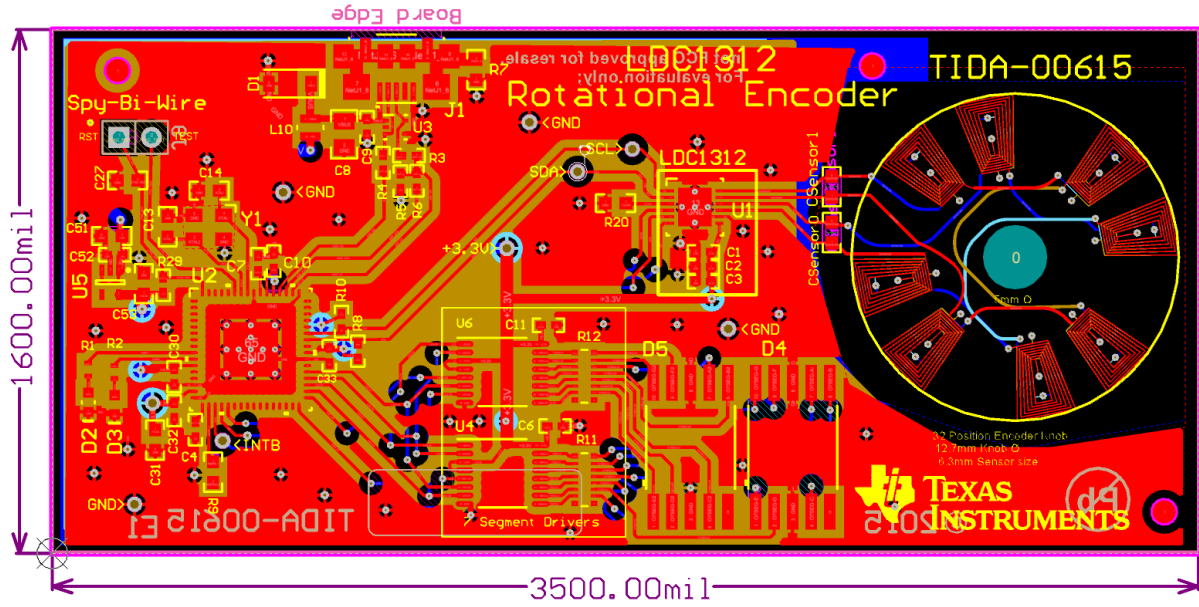


Figure 1: Multi-layer Sensor Print

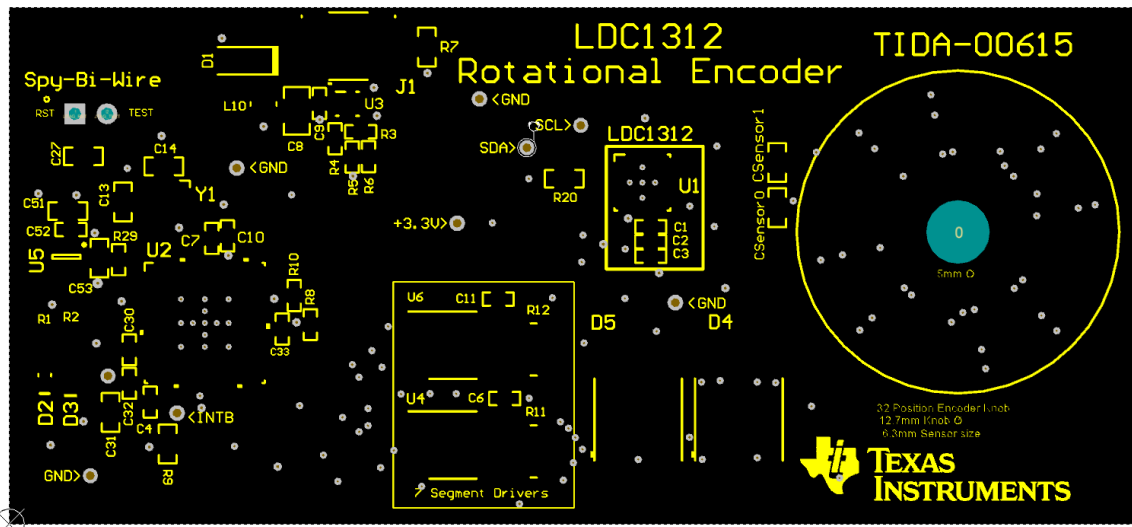


Figure 2: Sensor PCB Top Silkscreen

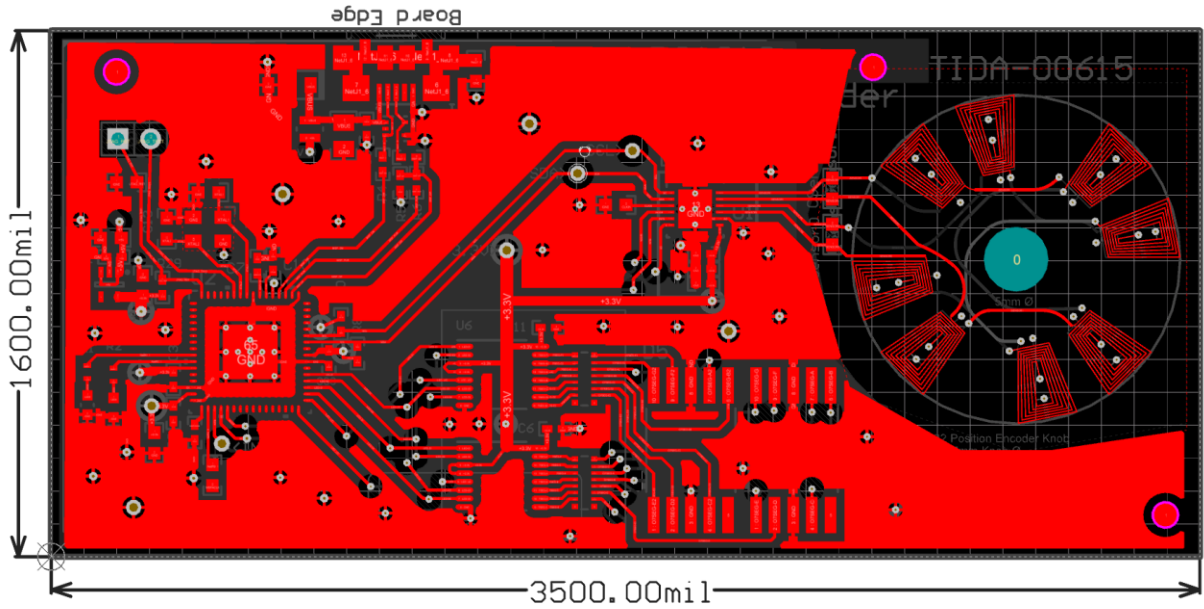


Figure 3: Sensor PCB Top Layer Routing

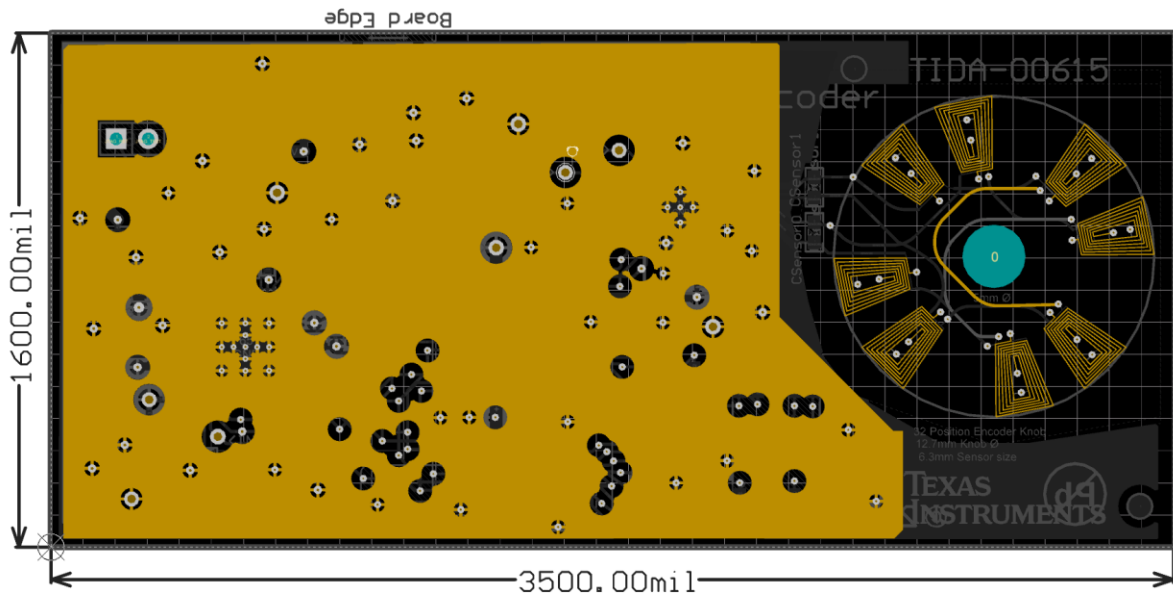


Figure 4: Sensor PCB Midlayer1 Routing

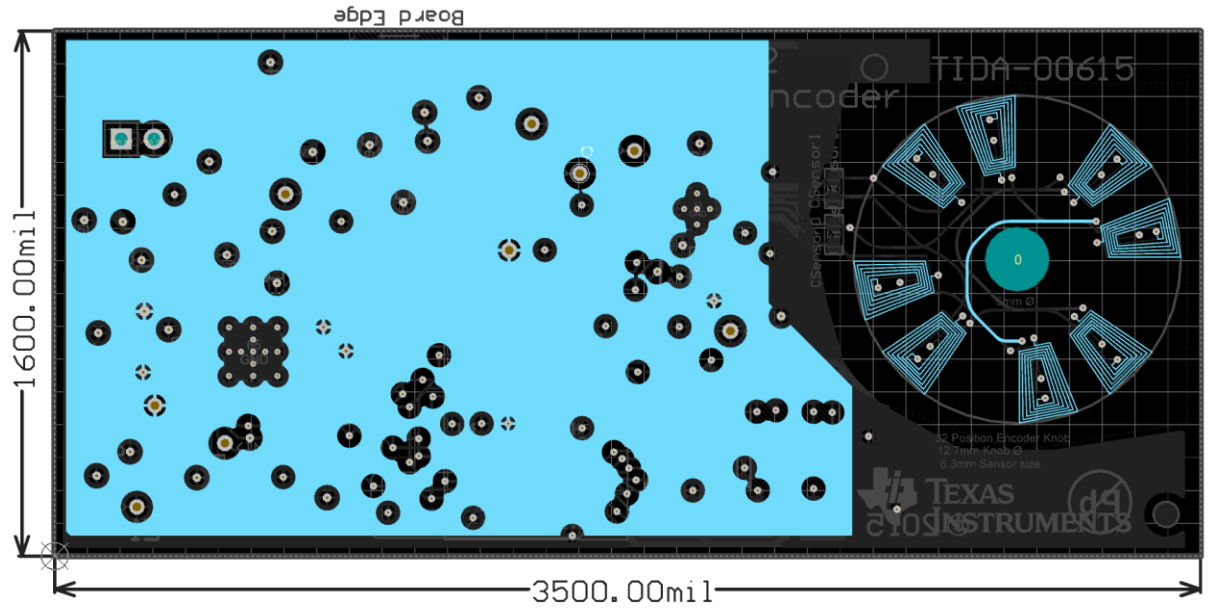


Figure 5: Sensor PCB Midlayer2 Routing

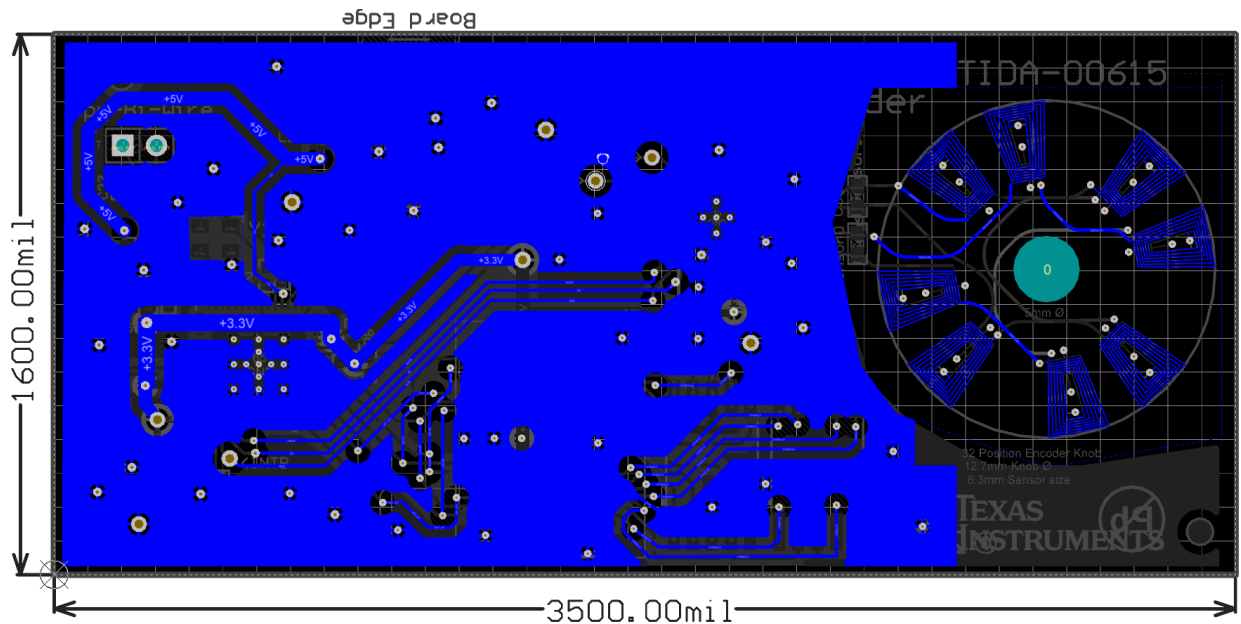


Figure 6: Sensor PCB Bottom Layer Routing

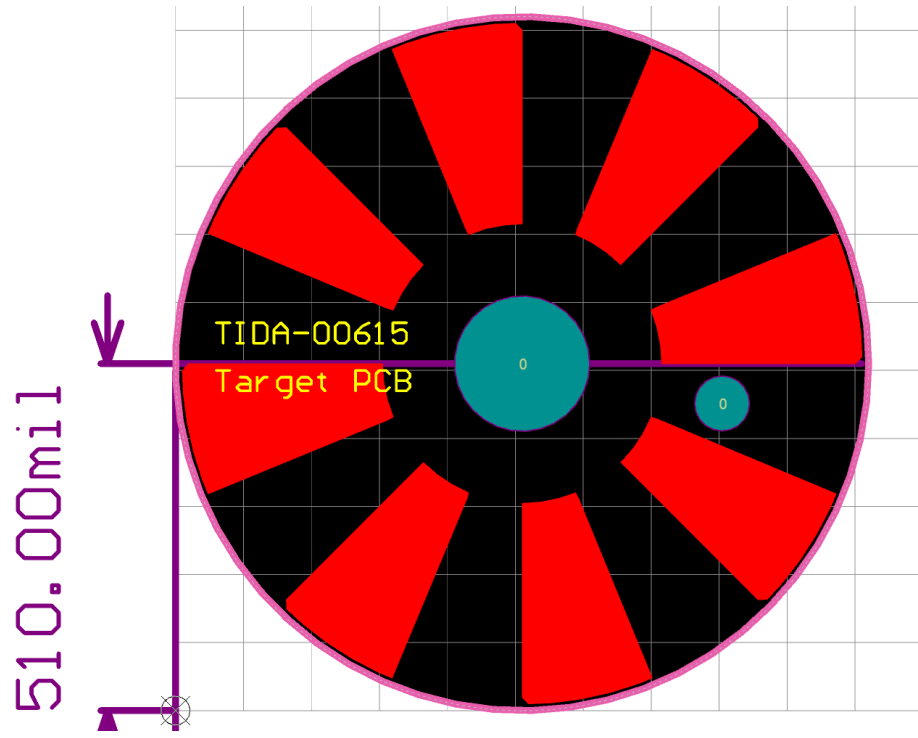


Figure 7: Target PCB Top Layer Routing

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